

MA379

Silicon epitaxial planer type

For UHF tuner

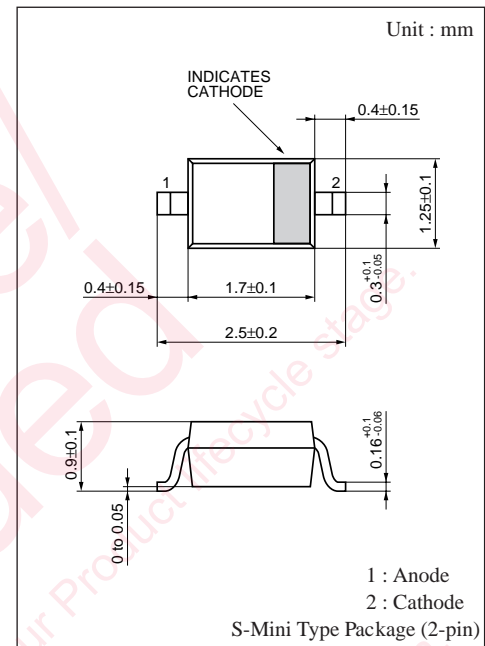
■ Features

- Large capacity variation ratio
- Small series resistance r_D
- S-Mini package, enabling down-sizing of the equipment and automatic insertion through taping

■ Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	V_R	32	V
Peak reverse voltage	V_{RM}^*	35	V
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	- 55 to +150	$^\circ\text{C}$

* $R_L = 10\text{k}\Omega$



Marking Symbol : 7L

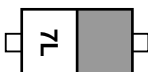
■ Electrical Characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Condition	min	typ	max	Unit
Reverse current (DC)	I_R	$V_R = 30\text{V}$			10	nA
Diode capacitance	$C_{D(2V)}$	$V_R = 2\text{V}, f = 1\text{MHz}$	5.50		6.84	pF
	$C_{D(25V)}$	$V_R = 25\text{V}, f = 1\text{MHz}$	0.84		1.05	pF
	$C_{D(10V)}$	$V_R = 10\text{V}, f = 1\text{MHz}$	1.80		2.38	pF
	$C_{D(17V)}$	$V_R = 17\text{V}, f = 1\text{MHz}$	1.03		1.36	pF
Capacitance ratio	$C_{D(2V)}/C_{D(25V)}$		6.0		7.0	—
Diode capacitance deviation	ΔC	$C_{D(2V)}(10V)(17V)(25V)$			2.0	%
Series resistance	r_D^*	$V_R = 5\text{V}, f = 470\text{MHz}$			1.0	Ω

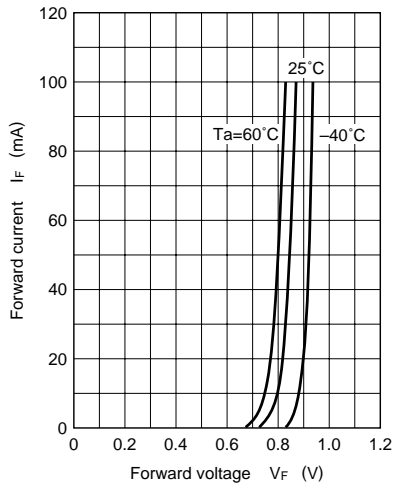
Note 1. Rated input/output frequency : 470MHz

2. * r_D measurement device : YHP MODEL 4191A RF IMPEDANCE ANALYZER

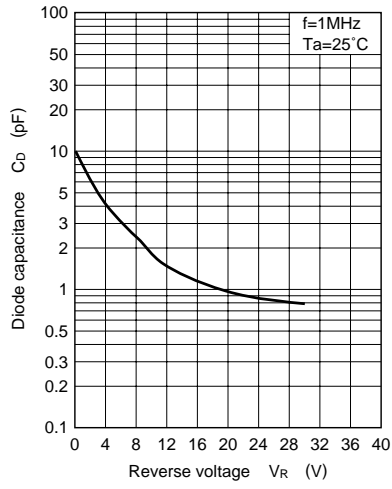
■ Marking



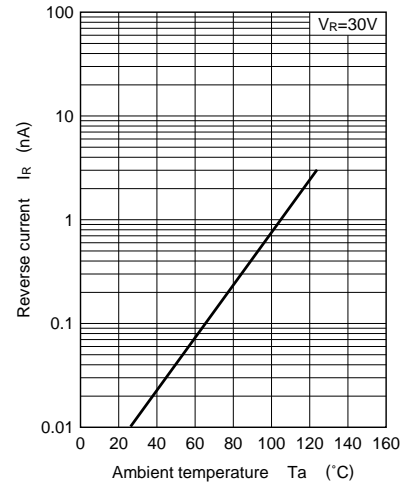
$I_F - V_F$



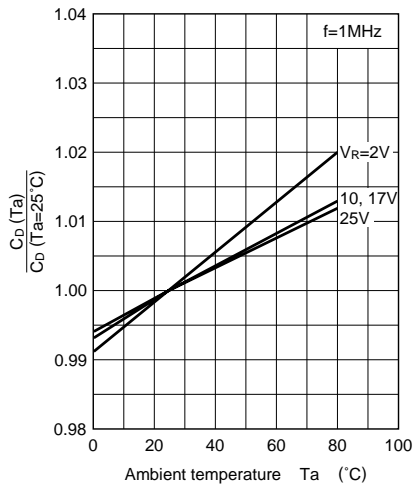
$C_D - V_R$



$I_R - T_a$



$C_D - T_a$



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